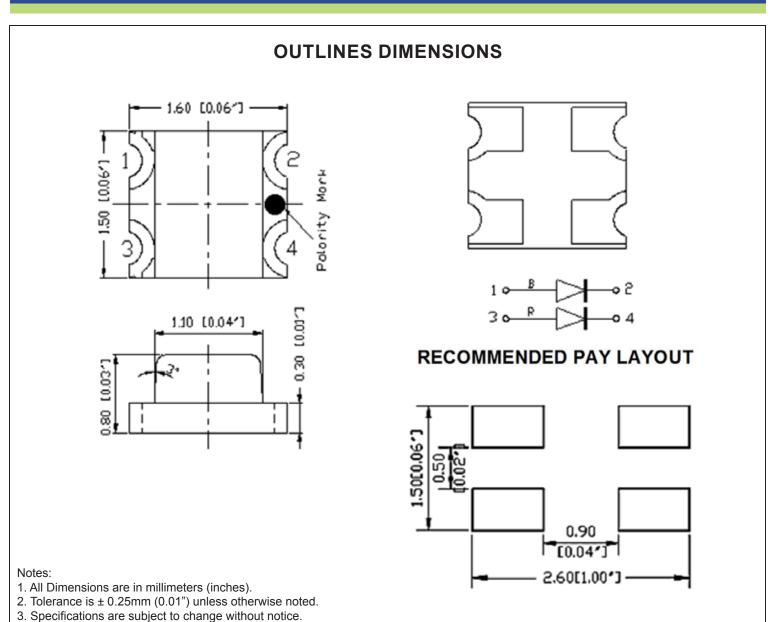


SPECIFICATIONS CS66R2B2C



Part Number	Chip Material	Color of Emission	Lens Type	Viewing Angle
CS66R2B2C	InGaAIP/InGaN	Red/Blue	Water Clear	140°





ABSOLUTE MAXIMUM RATINGS

(TA=25°C)

Parameter	Symbol	Color Max Rating		Unit			
Power Discipation	PD	Red	75	mW			
Power Dissipation	PD	Blue	111				
Pulse Current Forward Current	lfP	Red	125	mA			
Pulse Current Forward Current	IFP	Blue	125	IIIA			
Continuous Forward Current	lF	Red	30	mA			
Continuous Forward Current		Blue	30				
Reverse Voltage	VR	5		V			
Operating Temperature Range	Topr	-40	°C				
Storage Temperature Range	Тѕтс	-40~+85		°C			
IFP = Pulse Width ≤ 10 ms, Duty Rat	e Width ≤ 10 ms, Duty Ratio ≤1/10. Soldering Condition: 260 °C/ 5sec						

OPTICAL-ELECTRICAL CHARACTERISTICS

(TA=25°C)

Darameter	Symbol	Test Condi- tion	Color	Value			l lmit
Parameter				Min	Тур	Max	Unit
Luminous Intonsity	lv	I _F = 20mA	Red	50	80	-	mcd
Luminous Intensity			Blue	40	75	-	
Farward Valtage	VF	I _F = 20mA	Red	-	2.0	2.5	V
Forward Voltage			Blue	-	3.1	3.7	
Davaraa Laakaga Currant	lR	V _R = 5V	Red	-	-	10	μA
Reverse Leakage Current			Blue	-	-	10	
Viewing Angle	201/2	I _F = 20mA	Red	-	140	-	deg
Viewing Angle			Blue	-	140	-	
Dook Woyalangth	λР	I _F = 20mA	Red	-	640	-	nm
Peak Wavelength			Blue	-	465	-	
Dominant Wayalangth	λD	I _F = 20mA	Red	625	630	635	nm
Dominant Wavelength			Blue	465	470	475	

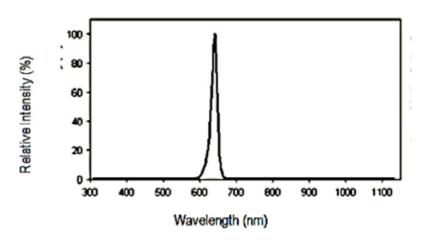
^{*}Tolerance of viewing angle: -10 / +5 deg.



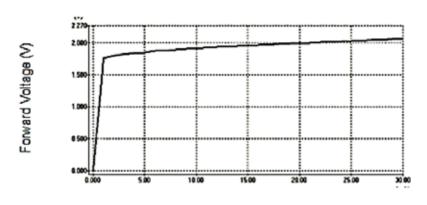


OPTICAL CHARACTERISTIC CURVES (RED)

Relative Intensity vs. Wavelength

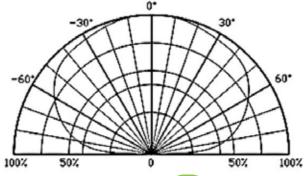


Forward Current vs. Forward Voltage



Forward Current (mA)

Directive Characteristics

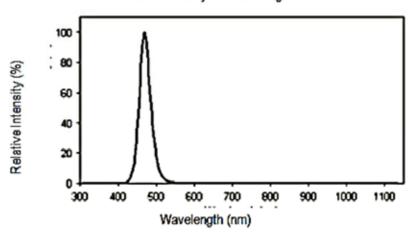


RoHS Compliant

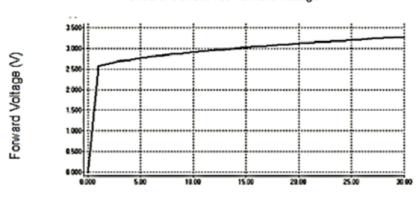


OPTICAL CHARACTERISTIC CURVES (BLUE)

Relative Intensity vs. Wavelength

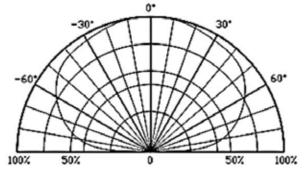


Forward Current vs. Forward Voltage



Forward Current (mA)

Directive Characteristics

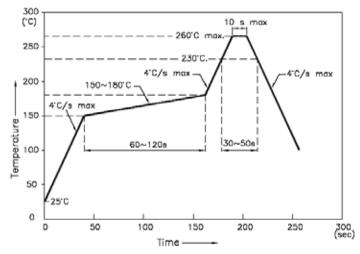


RoHS Compliant



SOLDERING CONDITIONS – LAMP TYPE LED

REFLOW PROFILE

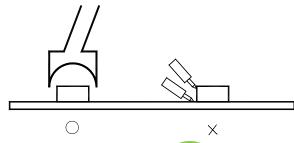


NOTES:

- 1. We recommend the reflow temperature 245°C (± 5 °C). The maximum soldering temperature should be limited to 260°C.
- 2. Do not cause stress to the epoxy resin while it is exposed to high temperature.
- 3. Number of reflow process shall be 2 times or less.
 - Soldering iron
 - Basic spec is \leq 5sec when 260°C. If temperature is higher, time should be shorter
 - (+10°C → -1sec). Power dissipation of iron should be smaller than 20W, and temperatures should be controllable .Surface temperature of the device should be under 230°C.

Rework

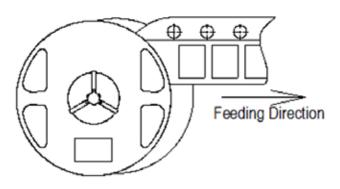
- 1. Customer must finish rework within 5 sec under 260°C.
- 2. The head of iron cannot touch copper foil
- 3. Twin-head type is preferred.



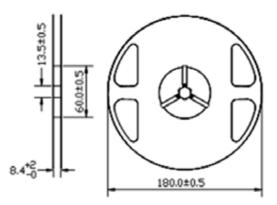


PACKAGING SPECIFICATIONS

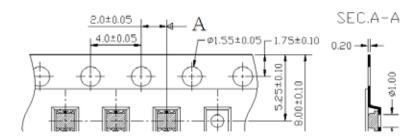
Feeding Direction



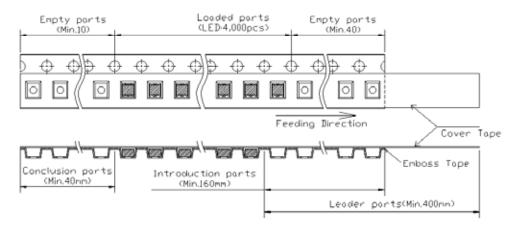
• Dimensions of Reel (Unit: mm)



Dimensi



•



Notes:

- 1. Empty component pockets are sealed with top cover tape;
- 2. The maximum number of missing lamps is two;
- 3. 4,000 pcs/Reel

